

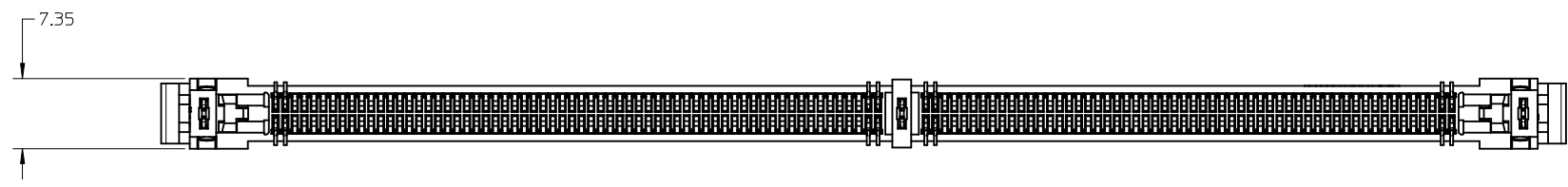
NOTES:

1. MATERIALS
HOUSING - HIGH TEMP LCP GLASS FILLED, UL 94V-0, BLACK
EJECTORS - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
2. PLATING OPTION - PLS REFER TO SHEET 5.
3. CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS. (MEASURED OVER PC PADS)
4. RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237. PLS REFER TO SHEET 3.
5. PRODUCT IS PACKED INTO TRAYS. WRAP IN MOISTURE BARRIER BAG WITH SILICA GEL.
6. MOLEX LOGO, DATE CODE & PART NO. INDICATED ON HOUSING.
7. DIMM MODULE SEATING PLANE FROM TOP OF PCB.
8. COPLANARITY FOR SOLDER TAILS SHALL NOT EXCEED 0.20MM.
9. REFER TO PRODUCT SPEC. PS-87966-001 FOR PERFORMANCE SPECIFICATIONS.
10. THE KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB, WHICH DOES NOT INCLUDE THE LATCH.
11. KEEP OUT ZONE AS PER JEDEC SO-001.
12. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

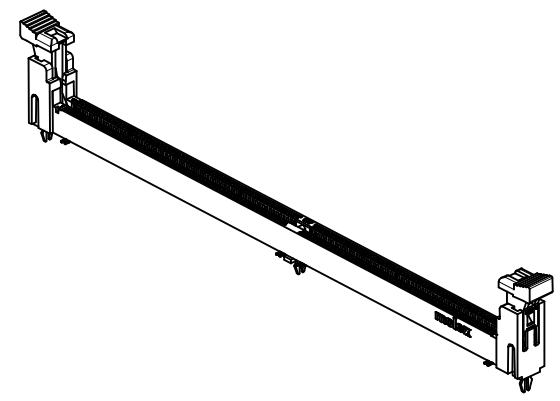
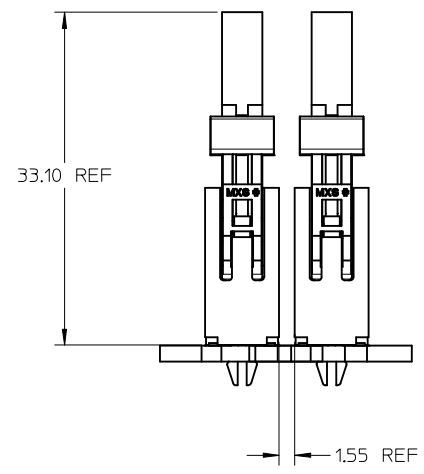
ADDED MBB & S.GEL EC NO: S2012-0451 DRW: CCTEH 2012/12/07 CHK: EKSOH 2013/01/03 APPR: SILENI 2013/01/03	REV B2	DESCRIPTION QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY CCTEH	DATE 2005/10/19	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, SMT			
			4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2005/11/21	<div style="text-align: center; font-size: 2em; font-weight: bold;">molex</div>			
			3 PLACES	± ---	± ---	APPROVED BY GGLEE	DATE 2005/11/21				
2 PLACES	± 0.10	± ---	MATERIAL NO.		SEE TABLE		DOCUMENT NO.	SHEET NO.			
1 PLACE	± ---	± ---	ANGULAR ± 1 °		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-87966-002	1 OF 5			
0 PLACE	±	±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								

10 9 8 7 6 5 4 3 2 1

F

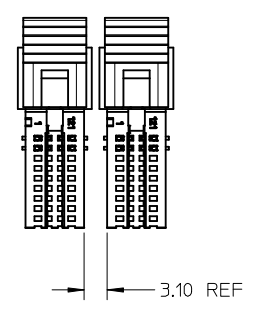


E



D

B



A

ADDED MBB & S.GEL
 IEC NO: S2012-0451
 DRW: CCTEH 2012/12/07
 CHY: DEKSOH 2013/01/03
 APPR: SHLENI 2013/01/03

REV	DESCRIPTION
B2	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
$\nabla_F = 0$	4 PLACES \pm ---	\pm ---
$\nabla_E = 0$	3 PLACES \pm ---	\pm ---
$\nabla_D = 0$	2 PLACES \pm 0.10	\pm ---
	1 PLACE \pm ---	\pm ---
	0 PLACE \pm	\pm

ANGULAR \pm 1 °
 DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

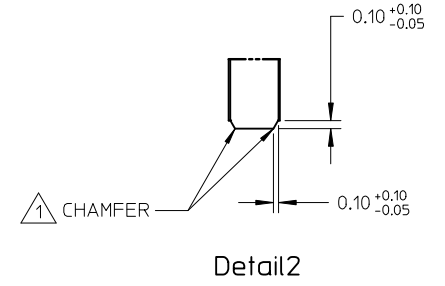
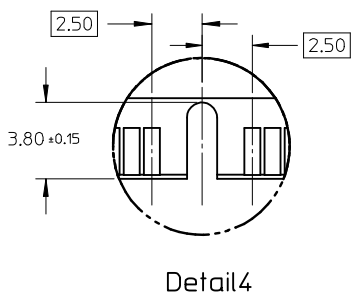
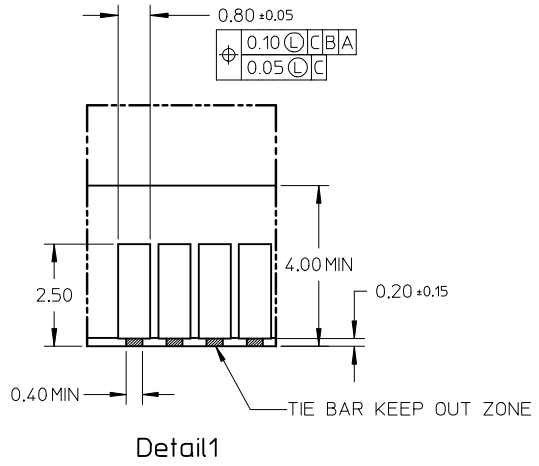
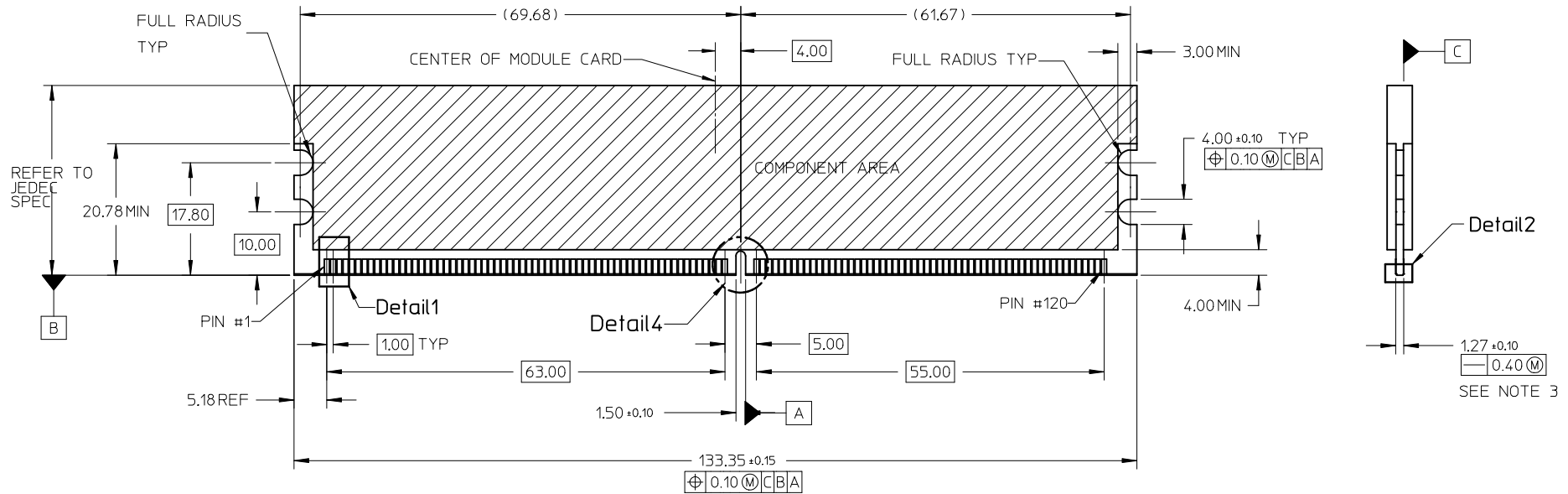
DIMENSION STYLE MM ONLY	
DRAWN BY CCTEH	DATE 2005/10/19
CHECKED BY SRRAMESH	DATE 2005/11/21
APPROVED BY GGLEE	DATE 2005/11/21
MATERIAL NO.	
SEE TABLE	

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, SMT		
molex		
DOCUMENT NO. SD-87966-002	SHEET NO. 2 OF 5	

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

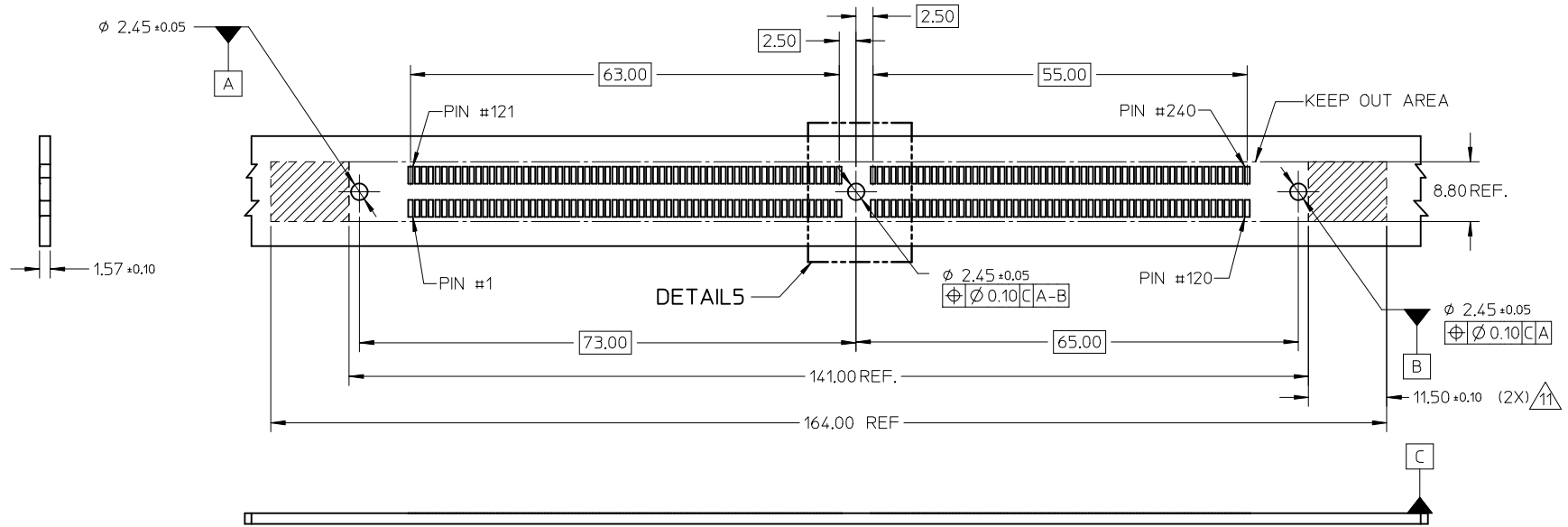
RECOMMENDED MODULE LAYOUT



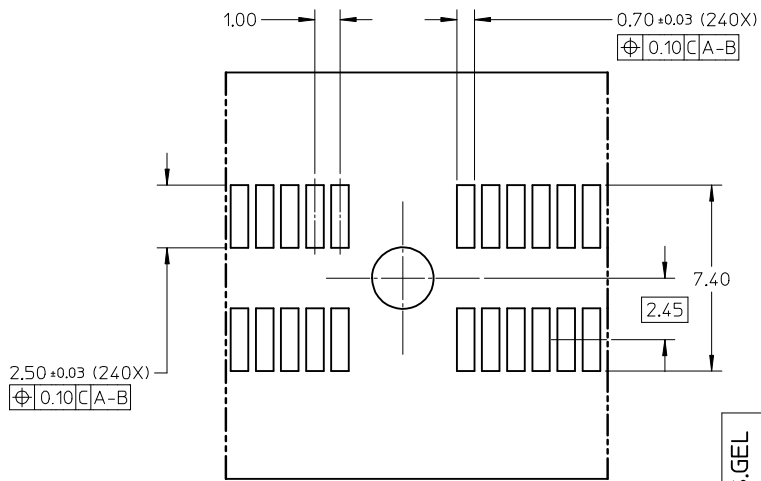
NOTES:
 1. MODULE CARD USED IN PRODUCT TESTING ARE CHAMFER.

ADDED MBB & S.GEL EC NO: S2012-0451 DRWN: CTEH 2012/12/07 CHKD: EKSOH 2013/01/03 APPR: SILENI 2013/01/03	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DIMENSION STYLE MM ONLY DRAWN BY DATE CTEH 2005/10/19 CHECKED BY DATE SRRAMESH 2005/11/21 APPROVED BY DATE GGLEE 2005/11/21 MATERIAL NO.	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, SMT	SHEET NO. 3 OF 5
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	ANGULAR ± 1 °	SEE TABLE	DOCUMENT NO. SD-87966-002	molex	
	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
	REV B2					
	DESCRIPTION					

9 8 7 6 5 4 3 2 1




RECOMMENDED STENCIL THICKNESS = 150µM.



DETAILS

ADDED MBB & S.GEL EC NO: S2012-0451 DRW: CCTEH 2012/12/07 CHK: DEKSOH 2013/01/03 APPR: SILENI 2013/01/03	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.10</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>0 PLACE</td> <td>±</td> <td>±</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.10	± ---	1 PLACE	± ---	± ---	0 PLACE	±	±	DIMENSION STYLE MM ONLY DRAWN BY: CCTEH DATE: 2005/10/19 CHECKED BY: SRRAMESH DATE: 2005/11/21 APPROVED BY: GGLEE DATE: 2005/11/21	SCALE NTS DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE DDR2 DIMM, 100MM PITCH 240 CKTS, SMT
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B2	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87966-002	SHEET NO. 4 OF 5																			
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ASSEMBLY PART NO.	VOLTAGE KEY POS.	PLATING	LATCH COLOR	LUBRICATION
87966-0001	CENTRE 1.8V	0.76µM (30µ IN) MIN. GOLD ON CONTACT 2.54µM (100µ IN) MIN. TIN ON SOLDER TAILS 1.27µM (50µ IN) MIN. NICKEL UNDERPLATE	BLACK	NO
87966-0002				YES

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	$\nabla_A = 0$ $\nabla_C = 0$ $\nabla_B = 0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± --- ± --- 0 PLACE ± ±	DRAWN BY CCTEH CHECKED BY SRRAMESH APPROVED BY GGLEE	DATE 2005/10/19 DATE 2005/11/21 DATE 2005/11/21	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, SMT					
		ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-87966-002					
	B2	REV			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			